NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL−C−26074, CLASS 1,
   100 TO 300 MICRONCHES (2.5um − 7.6um) THICK.
   GOLD PLATE PER MIL−G−45204, TYPE 3, GRADE A, CLASS 1
   (40 TO 80 MICRONCHES (1um − 2um) THICK).
   BODY SURFACE FINISH: VDI 21−24 (1.12−1.6 Ra).

3. PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
   AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO−220.